



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	承認 APPD.	承認 APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITTING	E.MURANO	Y.YAHIRO		K.HUETOMI

DESIGNATION

MM50-200B\*-B1

SERIES PREFIX シリーズ名  
NO. OF CONTACTS 芯数

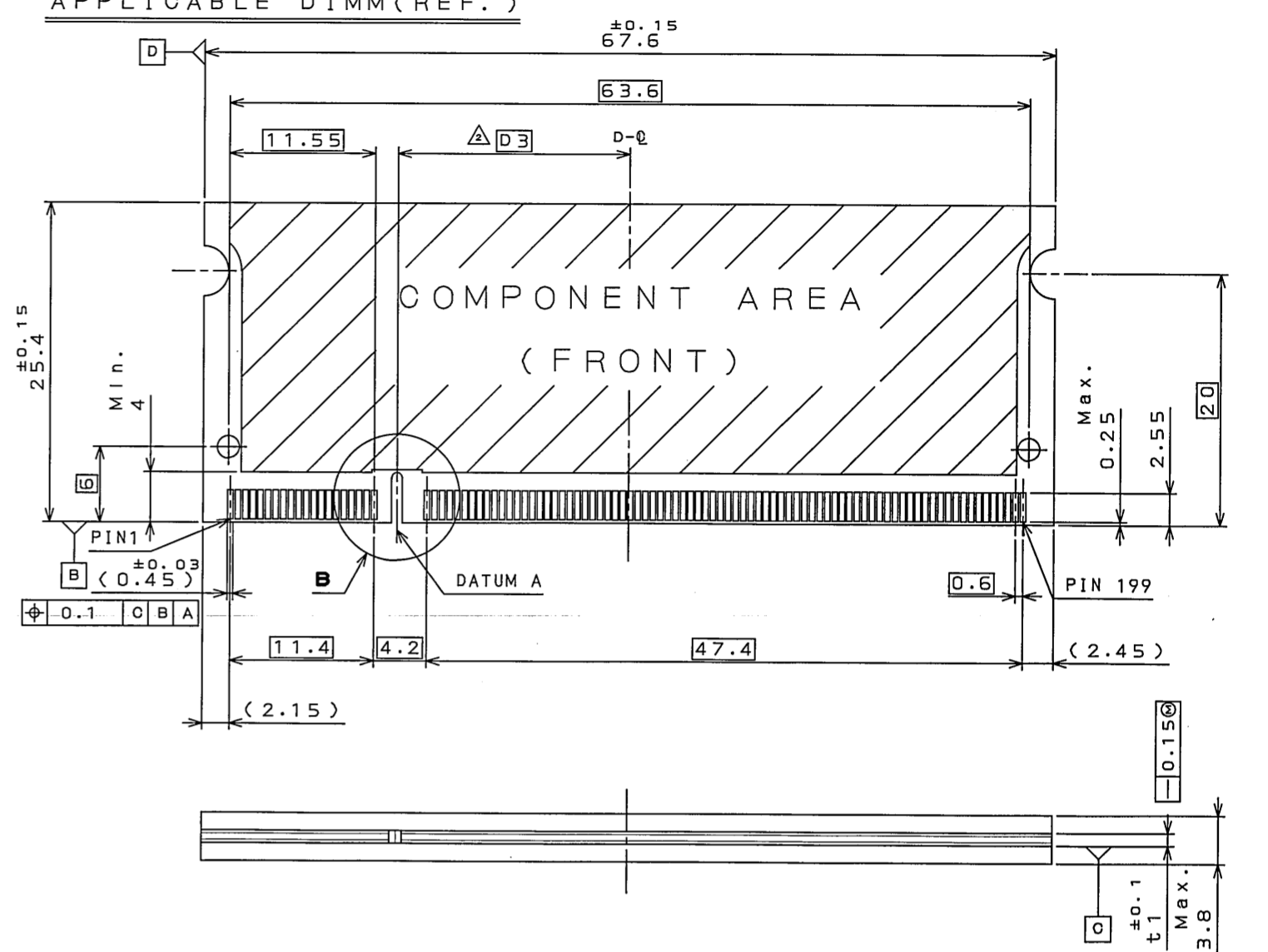
CONTACT FINISH 接点仕上げ  
1: Au(0.1μm MIN) OVER NI

MODIFY CODE モディファイコード  
B: 4.0mm HEIGHT

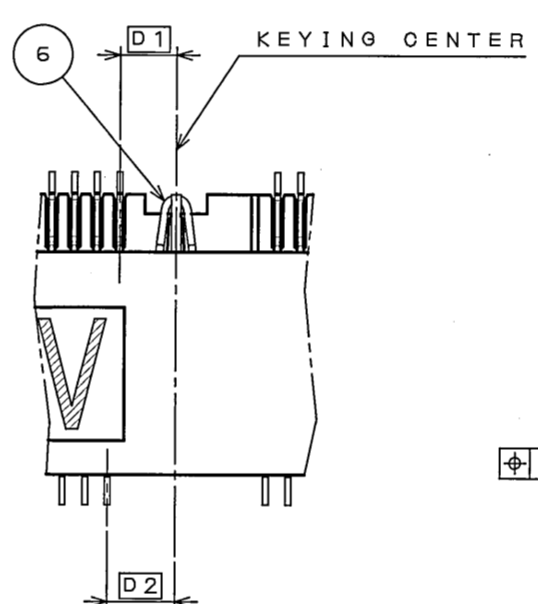
SOCKET TYPE ソケットタイプ  
B: LATCH TYPE SMT

KEYING TYPE (DETAIL A) キータイプ  
2: TYPE B(1.8V)  
1: TYPE A(2.5V)

APPLICABLE DIMM (REF.)



DETAIL A (SCALE 5:1) (REF. TABLE 1)



APPLICABLE P.C.B. DIMENSION (REF.)  
適合基板寸法(参考)

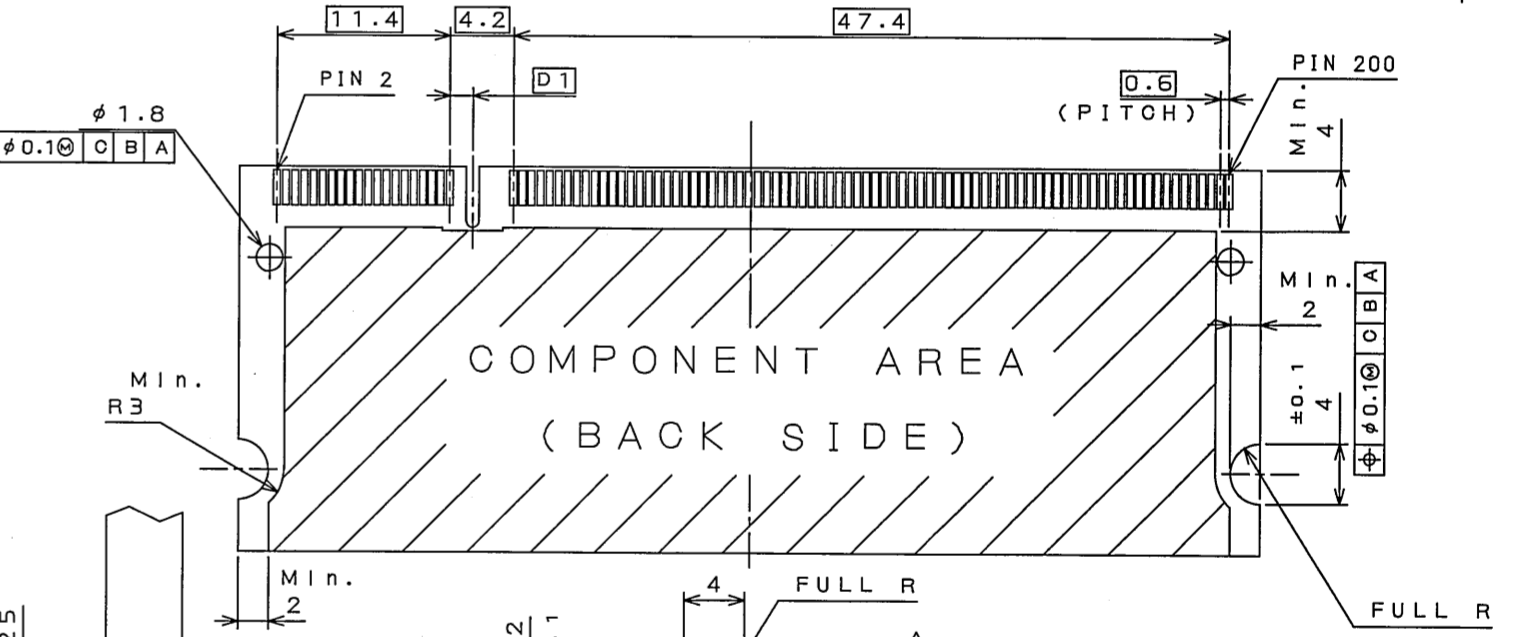
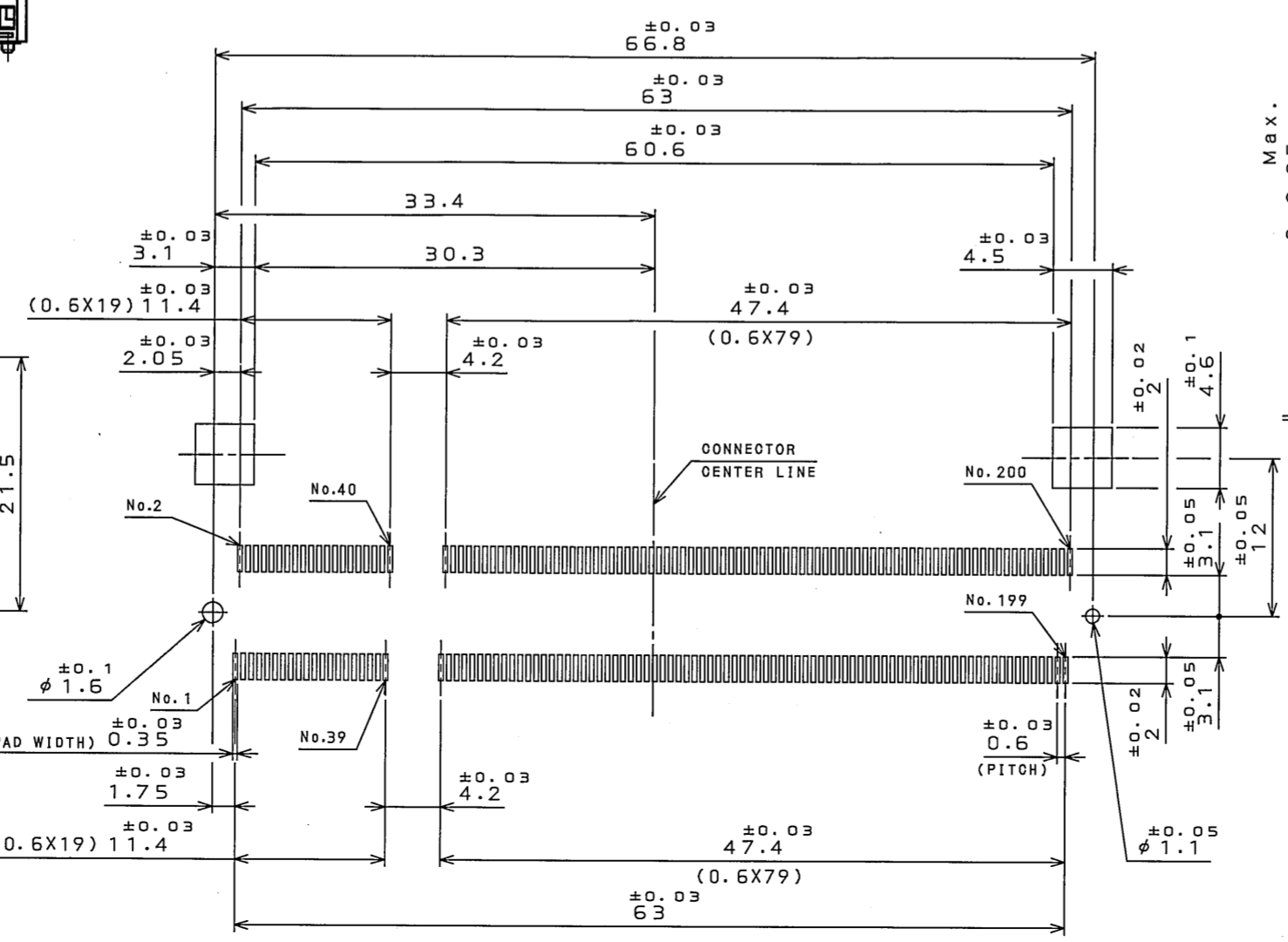
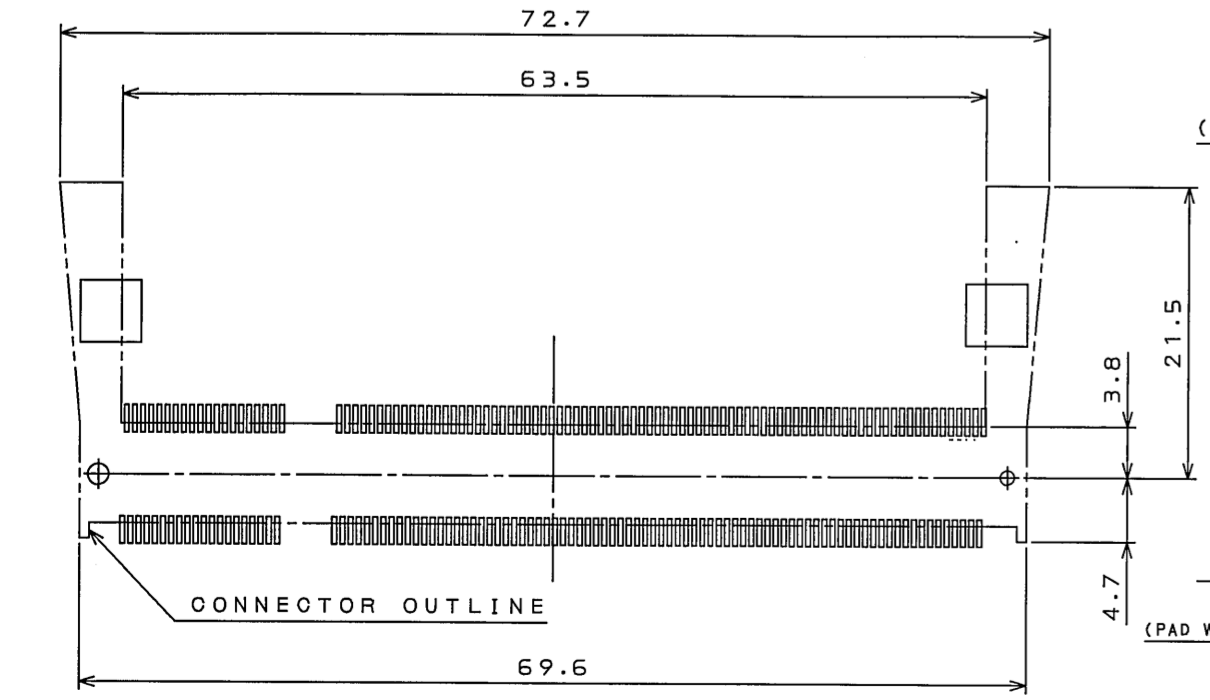
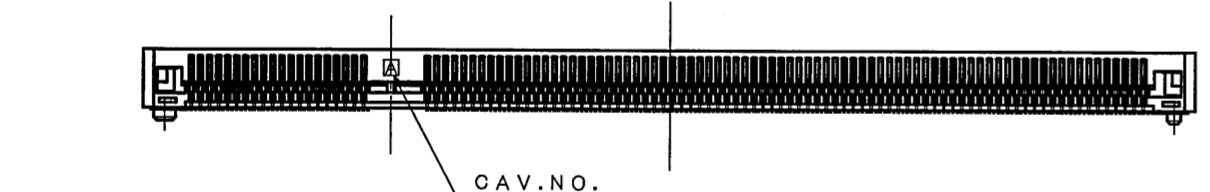
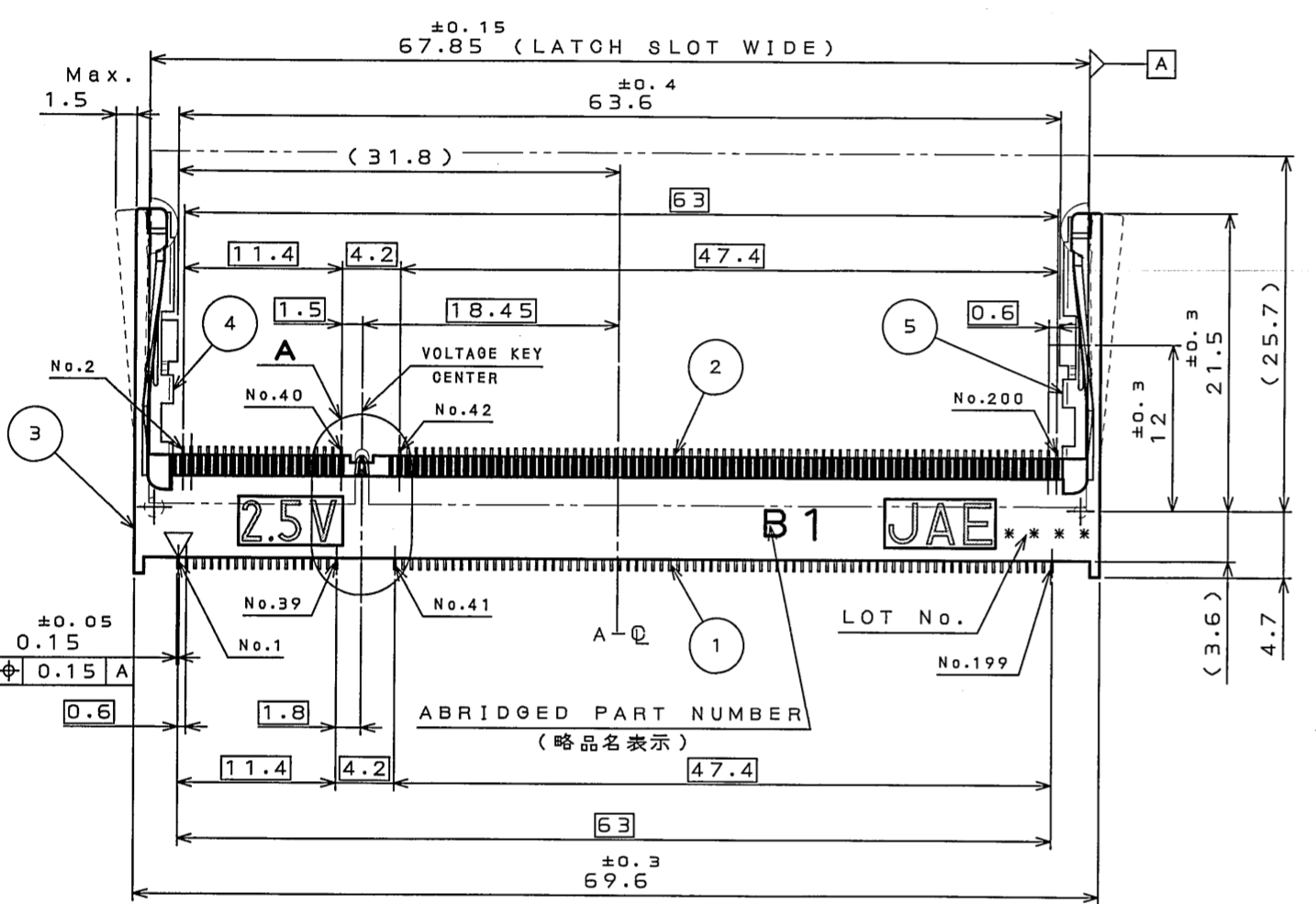
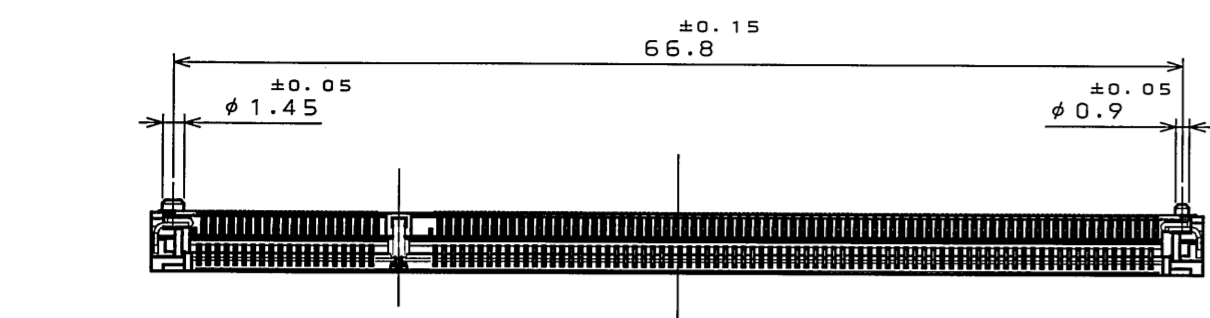


TABLE 1  
MECHANICAL KEYING

POWER SUPPLY	D1	D2	D3
2.5V (TYPE A)	1.5	1.8	18.45
1.8V (TYPE B)	2.4	2.7	17.55

6 KEY	1 STAINLESS		
5 HOLD DOWN	2 1 PHOSPHOR BRONZE	TIN PLATING	
4 HOLD DOWN	1 1 PHOSPHOR BRONZE	TIN PLATING	
3 INSULATOR	1 GLASS FILLED LCP		UL94 V-0 COLOR BLACK
2 BOTTOM SIDE CONTACT	1 0 PHOSPHOR BRONZE	CONTACT AREA: Au(0.1μm MIN) OVER NI SOLDERING AREA: GOLD FLASH OVER NI	
1 TOP SIDE CONTACT	1 0 PHOSPHOR BRONZE	CONTACT AREA: Au(0.1μm MIN) OVER NI SOLDERING AREA: GOLD FLASH OVER NI	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL
仕様書 (SPECIFICATION)		第1版 (ORIGINAL DATE)	尺度 (SCALE)
JACS-1655-01		9.AUG.2002	2:1
製図 DR.		製図 DR.	シ-ス (SERIES)
担当 CHK.		Y.YAHIRO	MM50
承認 APPD.			名称 (TITLE)
承認 APPD.		K.SUZUKI	MM50 -200B*-B1
質量 (MASS)			日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
			図面番号 (DRAWING NO.)
			SJ037105
			版数 (REV.)
			2



CONNECTOR MOUNTED AREA (REF.)

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